



Search Report

EIC 1700

STIC Database Tracking Number: 240646

To: CHRISTINE TIERNEY
Location: REM-8A19
Art Unit: 1700
Thursday, October 18, 2007

Case Serial Number: 10/662001

From: KENDRA BANKS
Location: EIC1700
REM-4B28 / REM-4A28
Phone: (571)272-2516

kendra.banks@uspto.gov

Search Notes

Examiner TIERNEY:

No Cases Reported

US 6,261,433



PATNO IS 6261433

DATE: OCTOBER 18, 2007
LIBRARY: PATENT
FILE: ALL

Your search request is:
PATNO IS 6261433

Number of PATENTS found with your search request through:
LEVEL 1... 1

Your search request has found 1 PATENT through Level 1.
To DISPLAY this PATENT press either the KWIC, FULL, CITE or SEGMENTS key.
To MODIFY your search request, press the M key (for MODIFY) and then the ENTER key.

For further explanation, press the H key (for HELP) and then the ENTER key.

LEVEL 1 - 1 PATENT

1. 6261433 , July 17, 2001 , Electro-chemical deposition system and method of electroplating on substrates, Landau, Uziel - Cleveland, Ohio, United States (US), 295678 (09), June 16, 1999 - ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS)., APPLIED MATERIALS, INC. P.O. BOX 450-SANTA CLARA, CALIFORNIA, 95052, Reel and Frame Number: 010031/0507, Applied Materials, Inc., Santa Clara, California, United States (US), United States company or corporation (02)

CORE TERMS: substrate, electrolyte, plating, deposition, layer, electrode, container, copper, cathode, anode ...

LEVEL 1 - 1 OF 1 PATENT

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

6261433

July 17, 2001

Electro-chemical deposition system and method of
electroplating on substrates

REISSUE: July 17, 2003 - Reissue Application filed Ex. Gp.: 1741; Re. S.N.
10/622,001 (O.G. October 28, 2003)

CERT-CORRECTION: May 28, 2002 - a Certificate of Correction was issued for this
patent (O.G. June 18, 2002)

APPL-NO: 295678 (09)

FILED-DATE: April 21, 1999

GRANTED-DATE: July 17, 2001

CORE TERMS: substrate, electrolyte, plating, deposition, layer, electrode,
container, copper, cathode, anode ...

6261433 OR 6,261,433

Your search request has found no ITEMS.

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6261433 OR 6,261,433

Your search request has found no CASES.

To edit the above request, use the arrow keys. Be sure to move the cursor to the end of the request before you enter it.

To enter a new search request, type it and press the ENTER key.

What you enter will be Search Level 1.

For further explanation, press the H key (for HELP) and then the ENTER key.

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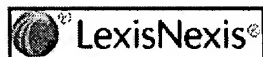
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Patent Search 6261433 10/18/2007

No cases found.

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Current session 18/10/2007

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18/10/07 15*42*14

Last connection: 17/10/07 14*08*32

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-GBFULL: Fulltext GB Applications released -see Fact Sheet
-2006 Euro and US Dollar price lists available from website
-FamPat: key full text content added; see details on website
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Query/Command : FILE PLUSPAT

QUESTEL - Time in minutes : 0,57

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	Estimated cost :	0.64 USD
Cost estimated for the last database search :		0.64 USD
Estimated total session cost	:	0.64 USD

Selected file: PLUSPAT

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Comprehensive Worldwide Patents database
Individual records for each Country or Patent Office
Coverage: 77 patenting authorities; start dates vary from 1800 forward
For PlusPat Fact Sheet, Pricing and FAQ, see the Questel.Orbit website
Citations and FI/F-term classification available for Japanese documents
Last update of file: 2007/10/12 (YYYY/MM/DD) 2007-41/UP (last update)

Search statement 1

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Query/Command : US6261433/PN

** SS 1: Results 1

Search statement 2

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Query/Command : PRT FULL NONSTOP LEGALALL

1 / 1 PLUSPAT - ©QUESTEL-ORBIT - image

PN - US6261433 B1 20010717 [US6261433]
TI - (B1) Electro-chemical deposition system and method of electroplating on substrates
PA - (B1) APPLIED MATERIALS INC (US)
PA0 - Applied Materials, Inc., Santa Clara CA [US]
IN - (B1) LANDAU UZIEL (US)
AP - US29567899 19990421 [1999US-0295678]
FD - Rel. Prov. 60/082,521 19980421 [1998US-P082521]
PR - US29567899 19990421 [1999US-0295678]
US8252198P 19980421 [1998US-P082521]
IC - (B1) C25D-005/00
ICAA - C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-007/12 [2006 C - I R M EP]
EC - C25D-007/12
PCL - ORIGINAL (O) : 205096000; CROSS-REFERENCE (X) : 204230200 204230700 204260000 204261000
204263000 204272000 204273000 204275100 204297010 204297030 205103000 205123000 205128000
205149000 205153000 205157000
DT - Basic
CT - US3649509; US3727620; US3770598; US4027686; US4092176; US4110176; US4113492; US4315059;
US4326940; US4336114; US4376685; US4405416; US4428815; US4435266; US4489740; US4510176;
US4518678; US4519846; US4693805; US4732785; US4789445; US5039381; US5055425; US5092975;
US5155336; US5162260; US5222310; US5224504; US5230743; US5252807; US5256274; US5259407;
US5290361; US5316974; US5328589; US5349978; US5368711; US5377708; US5429733; US5447615;
US5516412; US5608943; US5625170; US5651865; US5705223; US5718813; US5723028; JP58-182823;
JP63-118093; JP04131395; JP04280993; JP6017291; WO9712079; WO9925902; WO9925903; WO9925904;
WO9925905; WO9926275
PCT Written Opinion citing additional references for PCT/US 99/28159, dated Dec. 8, 2000.

PCT International Search Report dated Feb. 7, 2000.

Kenneth E. Pitney, "NEY Contact Manual," Electrical Contacts for Low Energy Uses, 1973, no month available.

Lucio Colombo, "Wafer Back Surface Film Removal," Central R&D, SGS-Thompson, Microelectronics, Agrate, Italy, 6 pages, no month/year available.

Semitoool.COPYRGT., Inc., "Metallization & Interconnect," 1998, 4 pages, no month available.

Verteq Online.COPYRGT., "Products Overview," 1996-1998, 5 pages, no month available.

Laurell Technologies Corporation, "Two control configurations available-see WS 400 OR WS-400Lite." Oct. 19, 1998, 6 pages.

Peter Singer, "Tantalum, Copper and Damascene: The Future of Interconnects," Semiconductor International, Jun. 1998, Pages cover, 91-92,94,96 & 98.

Peter Singer, "Wafer Processing," Semiconductor International, Jun., 1998, p. 70.

STG - (B1) U.S. Patent (no pre-grant pub.) after Jan. 2, 2001

AB - The invention provides an apparatus and a method for achieving reliable, consistent metal electroplating or electrochemical deposition onto semiconductor substrates. More particularly, the invention provides uniform and void-free deposition of metal onto metal seeded semiconductor substrates having sub-micron, high aspect ratio features. The invention provides an electrochemical deposition cell comprising a substrate holder, a cathode electrically contacting a substrate plating surface, an electrolyte container having an electrolyte inlet, an electrolyte outlet and an opening adapted to receive a substrate plating surface and an anode electrically connect to an electrolyte. Preferably, a vibrator is attached to the substrate holder to vibrate the substrate in at least one direction, and an auxiliary electrode is disposed adjacent the electrolyte outlet to provide uniform deposition across the substrate surface. Preferably, a periodic reverse current is applied during the plating period to provide a void-free metal layer within high aspect ratio features on the substrate.

UP - 2001-29

1 / 1 LGST - ©EPO

PN - US6261433 B1 20010717 [US6261433]

AP - US29567899 19990421 [1999US-0295678]

ACT - 20020528 US/CC-A
CERTIFICATE OF CORRECTION

20031028 US/RF-A
REISSUE APPLICATION FILED
EFFECTIVE DATE: 20030717

UP - 2003-45

1 / 1 CRXX - ©CLAIMS/RRX

PN - 6,261,433 A 20010717 [US6261433]

PA - Applied Materials Inc

ACT - 20030717 REISSUE REQUESTED
ISSUE DATE OF O.G.: 20031028
REISSUE REQUEST NUMBER: 10/622001
EXAMINATION GROUP RESPONSIBLE FOR REISSUEPROCESS: 1741

Reissue Patent Number:

Search statement 2

Query/Command : FILE INPADOC

LGST - Time in minutes : 0,01

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Estimated total session cost : 1.35 USD

CRXX - Time in minutes : 0,01

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Estimated total session cost :	7.36 USD

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The cost estimation below is based on Questel's standard price list

Estimated total session cost : 7.36 USD

PLUSPAT - Time in minutes : 0,38

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Estimated cost :	1.10 USD
Records displayed and billed :	1
Estimated cost :	1.55 USD
Cost estimated for the last database search :	2.65 USD
Estimated total session cost :	10.01 USD

Selected file: PLUSPAT

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Citations and FI/F-term classification available for Japanese documents

Last update of file: 2007/10/12 (YYYY/MM/DD) 2007-41/UP (last update)

Search statement 2

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Query/Command : FAM US6261433/PN

1 Patent Groups

**** SS 2: Results 13**

Search statement 3

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Query/Command : FAMSTATE NONSTOP

1 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - DE69829040 D1 20050324 [DE69829040]
STG - (D1) Granted EP number in bulletin
OTI - (D1) Elektroplattierungschemie
PA - (D1) APPLIED MATERIALS INC (US)
IN - (D1) D URSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC - (D1) C25D-003/38
AP - DE69829040 19981116 [1998DE-6029040]
PR - US8252198P 19980421 [1998US-P082521]
 US11486598 19980713 [1998US-0114865]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
UP - 2005-12

1 / 1 LEGALI - ©EPO

PN - DE69829040 D1 20050324 [DE69829040]
AP - DE69829040 19981116 [1998DE-6029040]
ACTE - 20060119 DE/8332-A [-]
 NO LEGAL EFFECT FOR DE
UP - 2006-03

2 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - DE69929967 D1 20060427 [DE69929967]
STG - (D1) Granted EP number in bulletin
OTI - (D1) ELEKTROPLATTIERUNGSSYSTEM UND VERFAHREN ZUR ELEKTROPLATTIERUNG AUF SUBSTRATEN
PA - (D1) APPLIED MATERIALS INC (US)
IN - (D1) LANDAU UZIEL (US)
IC - (D1) C25D-003/38 C25D-007/12 C25D-017/00
PN2 - DE69929967 T2 20070524 [DE69929967]
STG2 - (T2) Trans. Of EP patent
OTI2 - (T2) ELEKTROPLATTIERUNGSSYSTEM UND VERFAHREN ZUR ELEKTROPLATTIERUNG AUF SUBSTRATEN
PA2 - (T2) APPLIED MATERIALS INC (US)
IN2 - (T2) LANDAU UZIEL (US)
IC2 - (T2) C25D-003/38 C25D-007/12 C25D-017/00
AP - DE69929967 19990421 [1999DE-6029967]
PR - US8252198P 19980421 [1998US-P082521]
 WOUS9908782 19990421 [1999WO-US08782]
ICAA - C25D-017/00 [2006-01 A F I B H EP]; C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]

ICCA - C25D-017/00 [2006 C F I B H EP]; C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
EC - C25D-003/38
 C25D-007/12
UP - 2006-17

1 / 1 LEGALI - ©EPO

PN - DE69929967 D1 20060427 [DE69929967]
AP - DE69929967 19990421 [1999DE-6029967]
ACTE - 20070322 DE/8364-A [+]
 NO OPPOSITION DURING TERM OF OPPOSITION
UP - 2007-12

3 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - EP0952242 A1 19991027 [EP-952242]
STG - (A1) Public. Of applic. With search report
TI - (A1) Electro deposition chemistry
OTI - (A1) Elektroplattierungsschemie
 (A1) Chimie pour l'électroplacage
PA - (A1) APPLIED MATERIALS INC (US)
IN - (A1) D URSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC - (A1) C25D-003/38
PN2 - EP0952242 B1 20050216 [EP-952242]
STG2 - (B1) Patent
TI2 - (B1) Electro deposition chemistry
OTI2 - (B1) Elektroplattierungsschemie
 (B1) Chimie pour l'électroplacage
PA2 - (B1) APPLIED MATERIALS INC (US)
IN2 - (B1) D URSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC2 - (B1) C25D-003/38
LA - ENGLISH (ENG)
AP - EP98309351 19981116 [1998EP-0309351]
PR - US8252198P 19980421 [1998US-P082521]
 US11486598 19980713 [1998US-0114865]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
EC - C25D-003/38
 C25D-007/12
DS - BE DE GB IÉ NL
DT - Basic

1 / 1 LEGALI - ©EPO

PN - EP0952242 A1 19991027 [EP-952242]EP0952242 B1 20050216 [EP-952242]

AP - EP98309351 19981116 [1998EP-0309351]

ACTE - 19991027 EP/AK-A [+]
DESIGNATED CONTRACTING STATES:
BE DE GB IE NL

19991027 EP/AX-A [+]
EXTENSION OF THE EUROPEAN PATENT TO
AL;LT;LV;MK;RO;SI

20000308 EP/17P-A [+]
REQUEST FOR EXAMINATION FILED
EFFECTIVE DATE: 20000107

20000705 EP/AKX-A [+]
PAYMENT OF DESIGNATION FEES
BE DE GB IE NL

20010711 EP/17Q-A [+]
FIRST EXAMINATION REPORT
EFFECTIVE DATE: 20010528

20050216 EP/AK-A
DESIGNATED CONTRACTING STATES:
BE DE GB IE NL

20050216 EP/REG-A; GB/FG4D [+]
GB: EUROPEAN PATENT GRANTED
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20050323 EP/REG-A; IE/FG4D
IE: EUROPEAN PATENTS GRANTED DESIGNATING IRELAND
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20050324 EP/REF-A
CORRESPONDS TO:
(DE 69829040 20050324 [DE69829040])

20050801 EP/NLV1-A [-]
NL: LAPSED OR ANNULED DUE TO FAILURE TO FULFILL THE REQUIREMENTS OF ART. 29P
AND 29M OF THE PATENTS ACT; NO LEGAL EFFECT FROM

20060208 EP/26N-A [+]
NO OPPOSITION FILED
EFFECTIVE DATE: 20051117

20060405 EP/25-A [-]
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20060726 EP/GBPC-A [-]

GB: EUROPEAN PATENT CEASED THROUGH NON-PAYMENT OF RENEWAL FEE

EFFECTIVE DATE: 20051116

20060906 EP/REG-A; IE/MM4A [-]

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20061206 EP/25-A [-]

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EFFECTIVE DATE: 20051116

UP - 2007-17

4 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - EP0991795 A1 20000412 [EP-991795]
 STG - (A1) Public. Of applic. With search report
 TI - (A1) ELECTRO-CHEMICAL DEPOSITION SYSTEM AND METHOD OF ELECTROPLATING ON SUBSTRATES
 OTI - (A1) SYSTEME DE DEPOT ELECTROCHIMIQUE ET PROCEDE DE GALVANOPLASTIE SUR SUBSTRATS
 (A1) ELEKTROPLATTIERUNGSSYSTEM UND VERFAHREN ZUR ELEKTROPLATTIERUNG AUF SUBSTRATEN
 PA - (A1) APPLIED MATERIALS INC (US)
 IN - (A1) LANDAU UZIEL (US)
 IC - (A1) C25D-017/00
 PN2 - EP0991795 B1 20060222 [EP-991795]
 STG2 - (B1) Patent
 TI2 - (B1) ELECTRO-CHEMICAL DEPOSITION SYSTEM AND METHOD OF ELECTROPLATING ON SUBSTRATES
 OTI2 - (B1) ELEKTROPLATTIERUNGSSYSTEM UND VERFAHREN ZUR ELEKTROPLATTIERUNG AUF SUBSTRATEN
 (B1) SYSTEME DE DEPOT ELECTROCHIMIQUE ET PROCEDE DE GALVANOPLASTIE SUR SUBSTRATS
 PA2 - (B1) APPLIED MATERIALS INC (US)
 IN2 - (B1) LANDAU UZIEL (US)
 IC2 - (B1) C25D-003/38 C25D-007/12 C25D-017/00
 LA - ENGLISH (ENG)
 AP - EP99921429 19990421 [1999EP-0921429]
 PR - WOUS9908782 19990421 [1999WO-US08782]
 US8252198P 19980421 [1998US-P082521]
 ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
 ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
 DS - BE CH DE FR GB IE IT LI NL
 UP - 2000-13

1 / 1 LEGALI - ©EPO

PN - EP0991795 A1 20000412 [EP-991795]EP0991795 B1 20060222 [EP-991795]

AP - EP99921429 19990421 [1999EP-0921429]

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DESIGNATED CONTRACTING STATES:
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20000830 EP/17P-A [+]
REQUEST FOR EXAMINATION FILED
EFFECTIVE DATE: 20000706

20030502 EP/17Q-A [+]
FIRST EXAMINATION REPORT
EFFECTIVE DATE: 20030313

20060222 EP/AK-A [+]
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20060222 EP/REG-A; GB/FG4D [+]
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20060228 EP/REG-A; CH/EP [+]
CH: ENTRY IN THE NATIONAL PHASE
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20060322 EP/REG-A; IE/FG4D [+]
IE: EUROPEAN PATENTS GRANTED DESIGNATING IRELAND
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20060427 EP/REF-A
CORRESPONDS TO:
(DE 69929967 20060427 [DE69929967])

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NL: LAPSED OR ANNULED DUE TO FAILURE TO FULFILL THE REQUIREMENTS OF ART. 29P
AND 29M OF THE PATENTS ACT; NO LEGAL EFFECT FROM

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CH: PATENT CEASED
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OFFICE TO EPO

EFFECTIVE DATE: 20060222

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EFFECTIVE DATE: 20060222

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EFFECTIVE DATE: 20060222

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20070131 EP/26N-A [+]
NO OPPOSITION FILED
EFFECTIVE DATE: 20061123

20070420 EP/EN-A [-]
FR: TRANSLATION NOT FILED

UP - 2007-19

5 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - JP2002506488 T 20020226 [JP2002506488]
STG - (T) Unexam. Pat. Appl. On foreign appl.
IC - (T) C25D-017/00
AP - JP55332099T 19990421 [1999JP-0553320]
PR - US8252198P 19980421 [1998US-P082521]
WOUS9908782 19990421 [1999WO-US08782] /
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
UP - 2002-12

6 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - JP11310896 A 19991109 [JP11310896]
STG - (A) Doc. Laid open to publ. Inspec.
TI - (A) ELECTROPLATING METHOD
PA - (A) APPLIED MATERIALS INC
PA0 - (A) APPLIED MATERIALS INC
IN - (A) UJIRU RANDOO; DAVID B LEAR; JOHN J DURSO
IC - (A) C25D-003/38 C25D-005/00
PN2 - JP3510141 B2 20040322 [JP3510141]
STG2 - (B2) Grant. Pat. With A from 2500000 on
IC2 - (B2) C25D-005/54

AP - JP8620399 19990329 [1999JP-0086203]
PR - US8252198P 19980421 [1998US-P082521]
 US11486598 19980713 [1998US-0114865]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
FI - C25D3/38 101; C25D3/38 102; C25D5/00; C25D5/54
FTM - 4K023 AA19; 4K023 BA06; 4K023 BA08; 4K023 BA11; 4K023 BA12; 4K023 BA13; 4K023 BA15; 4K023 BA26; 4K023 BA29; 4K023 CA01; 4K023 CA09; 4K023 CB03; 4K023 CB07; 4K023 CB08; 4K023 CB11; 4K023 CB13; 4K023 CB19; 4K023 CB28; 4K023 CB32; 4K023 DA06; 4K024 AA09; 4K024 BA11; 4K024 BB12; 4K024 CA01; 4K024 CA02; 4K024 CB21; 4K024 GA16

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PN - TW531569 B 20030511 [TW-531569]
STG - (B) Patent
TI - (B) A solution and method for electrolytic plating of a metal on an electronically resistive substrate
PA - (B) APPLIED MATERIALS INC (US)
IN - (B) DURSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC - (B) C25D-003/00 C25D-005/24
AP - TW87118720 19981110 [1998TW-0118720]
PR - US11486598 19980713 [1998US-0114865]
 US8252198P 19980421 [1998US-P082521]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
UP - 2003-43

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PN - TW531569 B 20030511 [TW-531569]
AP - TW87118720 19981110 [1998TW-0118720]
ACTE - 20030905 TW/GD4A-A [+] ISSUE OF PATENT CERTIFICATE FOR GRANTED INVENTION PATENT
UP - 2004-28

8 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - US6113771 A 20000905 [US6113771]
STG - (A) United States patent
TI - (A) Electro deposition chemistry
PA - (A) APPLIED MATERIALS INC (US)
PA0 - Applied Materials, Inc., Santa Clara CA [US]
IN - (A) DURSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC - (A) C25D-005/02
AP - US11486598 19980713 [1998US-0114865]

PR - US11486598 19980713 [1998US-0114865]
 US8252198P 19980421 [1998US-P082521]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
EC - C25D-003/38
 C25D-007/12
PCL - ORIGINAL (O) : 205123000; CROSS-REFERENCE (X) : 106001220 106001250 106001260 205261000
 205296000 205297000 205298000
DT - Corresponding document
UP - 2000-35

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PN - US6113771 A 20000905 [US6113771]
AP - US11486598 19980713 [1998US-0114865]
ACTE - 20010508 US/CC-A
 CERTIFICATE OF CORRECTION
UP - 2003-22

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PN - US6261433 B1 20010717 [US6261433]
STG - (B1) U.S. Patent (no pre-grant pub.) after Jan. 2, 2001
TI - (B1) Electro-chemical deposition system and method of electroplating on substrates
PA - (B1) APPLIED MATERIALS INC (US)
PA0 - Applied Materials, Inc., Santa Clara CA [US]
IN - (B1) LANDAU UZIEL (US)
IC - (B1) C25D-005/00
AP - US29567899 19990421 [1999US-0295678]
PR - US29567899 19990421 [1999US-0295678]
 US8252198P 19980421 [1998US-P082521]
ICAA - C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-007/12 [2006 C - I R M EP]
EC - C25D-007/12
PCL - ORIGINAL (O) : 205096000; CROSS-REFERENCE (X) : 204230200 204230700 204260000 204261000
 204263000 204272000 204273000 204275100 204297010 204297030 205103000 205123000 205128000
 205149000 205153000 205157000
DT - Basic
UP - 2001-29

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PN - US6261433 B1 20010717 [US6261433]
AP - US29567899 19990421 [1999US-0295678]

ACTE - 20020528 US/CC-A
CERTIFICATE OF CORRECTION

20031028 US/RF-A
REISSUE APPLICATION FILED
EFFECTIVE DATE: 20030717

UP - 2003-45

10 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - US2003205474 A1 20031106 [US20030205474]
STG - (A1) Utility Patent Application published on or after January 2, 2001
TI - (A1) Electro deposition chemistry
PA - (A1) APPLIED MATERIALS INC (US)
PA0 - Applied Materials, Inc., [US]
IN - (A1) D URSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC - (A1) C25D-003/00 H01M-004/02 H01M-004/29 H01M-010/44
AP - US41000103 20030409 [2003US-0410001]
PR - US41000103 20030409 [2003US-0410001]
 US99211701 20011113 [2001US-0992117]
 US48461600 20000118 [2000US-0484616]
 US11486598 19980713 [1998US-0114865]
 US8252198P 19980421 [1998US-P082521]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
EC - C25D-003/38
 C25D-007/12
PCL - ORIGINAL (O) : 205057000
DT - Corresponding document
UP - 2003-46

11 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - US6350366 B1 20020226 [US6350366]
STG - (B1) U.S. Patent (no pre-grant pub.) after Jan. 2, 2001
TI - (B1) Electro deposition chemistry
PA - (B1) APPLIED MATERIALS INC (US)
PA0 - Applied Materials, Inc., Santa Clara CA [US]
IN - (B1) D URSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC - (B1) C25D-003/38 C25D-007/12
AP - US48461600 20000118 [2000US-0484616]
PR - US48461600 20000118 [2000US-0484616]
 US11486598 19980713 [1998US-0114865]
 US8252198P 19980421 [1998US-P082521]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]

ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
EC - C25D-003/38
 C25D-007/12
PCL - ORIGINAL (O) : 205182000; CROSS-REFERENCE (X) : 205186000 205291000 205296000
DT - Corresponding document
UP - 2002-10

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PN - US6350366 B1 20020226 [US6350366]
AP - US48461600 20000118 [2000US-0484616]
ACTE - 20000118 US/AS-A
 ASSIGNMENT
 OWNER: APPLIED MATERIALS, INC. P.O. BOX 450-A SANTA CLARA; EFFECTIVE DATE: 19980702
 ASSIGNMENT OF ASSIGNORS INTEREST;ASSIGNORS:LANDAU, UZIEL;D'URSO, JOHN J.;REAR,
 DAVID B.;REEL/FRAME:010552/0717

 20030708 US/CC-A
 CERTIFICATE OF CORRECTION
UP - 2004-26

12 / 13 PLUSPAT - ©QUESTEL-ORBIT

PN - US2002063064 A1 20020530 [US20020063064]
STG - (A1) Utility Patent Application published on or after January 2, 2001
TI - (A1) Electro deposition chemistry
PA - (A1) APPLIED MATERIALS INC (US)
PA0 - Applied Materials, Inc., Santa Clara CA [US]
IN - (A1) D URSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC - (A1) C25D-003/38
PN2 - US6610191 B2 20030826 [US6610191]
STG2 - (B2) U.S. Patent (with pre-grant pub.) after Jan. 2, 2001
TI2 - (B2) Electro deposition chemistry
PA2 - (B2) APPLIED MATERIALS INC (US)
IN2 - (B2) D URSO JOHN J (US); LANDAU UZIEL (US); REAR DAVID B (US)
IC2 - (B2) C25D-005/02
AP - US99211701 20011113 [2001US-0992117]
PR - US99211701 20011113 [2001US-0992117]
 US48461600 20000118 [2000US-0484616]
 US11486598 19980713 [1998US-0114865]
 US8252198P 19980421 [1998US-P082521]
ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]
ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]
EC - C25D-003/38
 C25D-007/12

PCL - ORIGINAL (O) : 205261000; CROSS-REFERENCE (X) : 205291000 205296000 205123000 205159000
205182000 205198000 205186000

DT - Corresponding document

UP - 2002-24

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PN - US2002063064 A1 20020530 [US20020063064]US6610191 B2 20030826 [US6610191]

AP - US99211701 20011113 [2001US-0992117]

ACTE - 20011113 US/AS-A
ASSIGNMENT
OWNER: APPLIED MATERIALS, INC. P.O. BOX 450-ASANTA CLARA,; EFFECTIVE DATE: 19980702
ASSIGNMENT OF ASSIGNORS INTEREST;ASSIGNORS:LANDAU, UZIEL /AR;REEL/
FRAME:012329/0114

20031209 US/CC-A
CERTIFICATE OF CORRECTION

UP - 2006-03

13 / 13 PLUSPAT - ©QUESTEL-ORBIT - image

PN - WO9954527 A2 19991028 [WO9954527]

STG - (A2) Publ. Of int. Appl. W/out int. Search rep

TI - (A2) ELECTRO-CHEMICAL DEPOSITION SYSTEM AND METHOD OF ELECTROPLATING ON SUBSTRATES

OTI - (A2) SYSTEME DE DEPOT ELECTROCHIMIQUE ET PROCEDE DE GALVANOPLASTIE SUR SUBSTRATS

PA - (A2) APPLIED MATERIALS INC (US)

PA0 - APPLIED MATERIALS, INC. ; 3050 Bowers Avenue Santa Clara, CA 95054 (US)

IN - (A2) LANDAU UZIEL

IC - (A2) C25D-017/00

PN2 - WO9954527 A3 20000323 [WO9954527]

STG2 - (A3) Subsqu. Publ. Of int. Search report

TI2 - (A3) ELECTRO-CHEMICAL DEPOSITION SYSTEM AND METHOD OF ELECTROPLATING ON SUBSTRATES

OTI2 - (A3) SYSTEME DE DEPOT ELECTROCHIMIQUE ET PROCEDE DE GALVANOPLASTIE SUR SUBSTRATS

PA2 - (A3) APPLIED MATERIALS INC (US)

IN2 - (A3) LANDAU UZIEL

IC2 - (A3) C25D-007/12 C25D-017/00

LA - ENGLISH (ENG)

AP - WO9908782 19990421 [1999WO-US08782]

PR - US8252198P 19980421 [1998US-P082521]

ICAA - C25D-003/38 [2006-01 A - I R M EP]; C25D-007/12 [2006-01 A - I R M EP]

ICCA - C25D-003/38 [2006 C - I R M EP]; C25D-007/12 [2006 C - I R M EP]

EC - C25D-003/38
C25D-007/12
DS - JP; KR; SG; European Patent (AT; BE; CH; CY; DE; DK; ES; FI; FR; GB; GR; IE; IT; LU; MC; NL; PT; SE)
DT - Corresponding document

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PN - WO9954527 A2 19991028 [WO9954527]WO9954527 A3 20000323 [WO9954527]
AP - WOUS9908782 19990421 [1999WO-US08782]
ACTE - 19991028 WO/AK [+]
DESIGNATED STATES CITED IN A SUBSEQUENTLY PUBLISHED SEARCH REPORT
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19991028 WO/AL [+]
DESIGNATED COUNTRIES FOR REGIONAL PATENTS CITED IN A SUBSEQUENTLY PUBLISHED
SEARCH REPORT
AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE

19991229 WO/121
EP: THE EPO HAS BEEN INFORMED BY WIPO THAT EP WAS DESIGNATED IN THIS
APPLICATION

20000323 WO/AK [+]
DESIGNATED STATES CITED IN A SUBSEQUENTLY PUBLISHED SEARCH REPORT
JP KR SG

20000323 WO/AL [+]
DESIGNATED COUNTRIES FOR REGIONAL PATENTS CITED IN A SUBSEQUENTLY PUBLISHED
SEARCH REPORT
AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE

UP - 2003-22

Search statement 3